

ESPI Current Report

Number: 18/2021
Date: 8 October 2021
Company: XTPL S.A., a joint stock company with its registered office in Wrocław

Topic: Filing a patent application for the development of a conductive mesh printing method with the possibility of transferring the mesh onto other substrates

Legal basis: Article 17(1) MAR – inside information

Contents of the Report: The Management Board of XTPL S.A. ("Issuer", "Company", "XTPL") hereby announces that on 8 October 2021, the Issuer filed a patent application with the United States Patent and Trademark Office (USPTO) relating to the XTPL-developed technological solution ("Method") for printing conductive mesh and transferring it onto other substrates.

The Method described in the application concerns the printing of conductive mesh on a particular substrate from which it can be transferred onto another substrate. Currently, XTPL's solution for transferring the printed mesh from one substrate to another is unique in the world and so far unattainable by any available method. Built of longitudinal and transverse lines that conduct electricity, the conductive mesh is used to create transparent conductive layers, which do not absorb light while conducting electricity and can be used as electrodes, e.g. in OLED displays.

The invention affords considerable freedom in designing devices that incorporate conductive mesh. For example, it will be possible to print conductive mesh on a glass substrate, and then transfer it onto a flexible substrate. This Method will simplify the current process of industrial production of microelectronic devices that use conductive mesh.

Obtaining patent protection in this area will allow the Issuer to increase its competitive edge by optimizing the electrical parameters of the mesh without substrate-related limitations.

The Issuer's Management Board has decided that the submission of the said patent application is inside information, as in the case of an entity operating in the deep-tech sector, effective protection by the Company of its intellectual and industrial property, a factor which influences the Company value, is one of

the elements that investors may take into account when making decisions about the Issuer's financial instruments.

In the opinion of the Company's Management Board, ensuring an appropriate level of security and extensive patent protection (both in the form of obtained patents and submitted patent applications) is a significant competitive advantage for the Issuer and may contribute to ensuring an appropriate bargaining position when negotiating commercial contracts.

Accordingly, in the Management Board's opinion, the information on submission of the patent application meets the criteria of inside information within the meaning of Article 7(1) MAR.

Signatures of the Company's representatives:

Jacek Olszański
MANAGEMENT BOARD MEMBER